



**THE DATASHEET OF
RSFDL RVG**



0.5A, 50V - 1000V Surface Mount Fast Recovery Rectifiers

FEATURES

- Glass passivated junction chip
- Ideal for automated placement
- High temperature metallurgically bonded construction
- Fast switching for high efficiency
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition



Sub SMA



MECHANICAL DATA

Case: Sub SMA

Molding compound, UL flammability classification rating 94V-0

Moisture sensitivity level: level 1, per J-STD-020

Part No. with suffix "H" means AEC-Q101 qualified

Packing code with suffix "G" means green compound (halogen-free)

Terminal: Matte tin plated leads, solderable per JESD22-B102

Meet JESD 201 class 2 whisker test

Polarity: Indicated by cathode band

Weight: 0.019 g (approximately)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)									
PARAMETER	SYMBOL	RSF AL	RSF BL	RSF DL	RSF GL	RSF JL	RSF KL	RSF ML	UNIT
Marking code		FAL	FBL	FDL	FGL	FJL	FKL	FML	
Maximum repetitive peak reverse voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum average forward rectified current	I _{F(AV)}	0.5							A
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	10							A
Maximum instantaneous forward voltage (Note 1) @ 0.5 A	V _F	1.3							V
Maximum reverse current @ rated V _R	I _R	5 50							μA
		T _J =25°C T _J =125°C							
Typical junction capacitance (Note 2)	C _J	4							pF
Maximum reverse recovery time (Note 3)	t _{rr}	150			250		500		ns
Typical thermal resistance	R _{θJC} R _{θJA}	32 150							°C/W
Operating junction temperature range	T _J	- 55 to +150							°C
Storage temperature range	T _{STG}	- 55 to +150							°C

Note 1: Pulse test with PW=300μs, 1% duty cycle

Note 2: Measured at 1 MHz and Applied VR=4.0 Volts.

Note 3: Reverse Recovery Test Conditions: I_F=0.5A, I_R=1.0A, I_{RR}=0.25A

ORDERING INFORMATION					
PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
RSFxL (Note 1)	H	RU	G	Sub SMA	1,800 / 7" Plastic reel (8mm tape)
		RV		Sub SMA	3,000 / 7" Plastic reel (8mm tape)
		RT		Sub SMA	7,500 / 13" Paper reel (8mm tape)
		MT		Sub SMA	7,500 / 13" Plastic reel (8mm tape)
		RQ		Sub SMA	10,000 / 13" Paper reel (8mm tape)
		MQ		Sub SMA	10,000 / 13" Plastic reel (8mm tape)
		R3		Sub SMA	1,800 / 7" Plastic reel (12mm tape)
		RF		Sub SMA	3,000 / 7" Plastic reel (12mm tape)
		R2		Sub SMA	7,500 / 13" Paper reel (12mm tape)
		M2		Sub SMA	7,500 / 13" Plastic reel (12mm tape)
		RH		Sub SMA	10,000 / 13" Paper reel (12mm tape)
		MH		Sub SMA	10,000 / 13" Plastic reel (12mm tape)

Note 1: "x" defines voltage from 50V (RSFAL) to 1000V (RSFML)

EXAMPLE					
PREFERRED PART NO.	PART NO.	PART NO. SUFFIX	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
RSFMLHRUG	RSFML	H	RU	G	AEC-Q101 qualified Green compound

RATINGS AND CHARACTERISTICS CURVES ($T_A=25^\circ\text{C}$ unless otherwise noted)

FIG. 1 FORWARD CURRENT DERATING CURVE

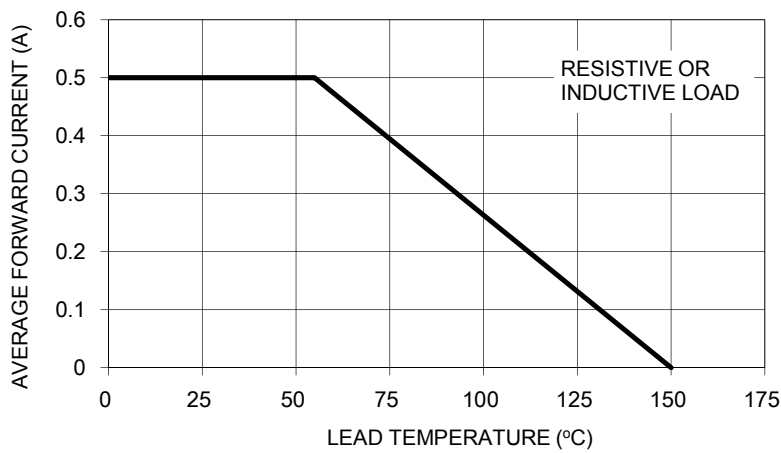


FIG. 2 TYPICAL REVERSE CHARACTERISTICS

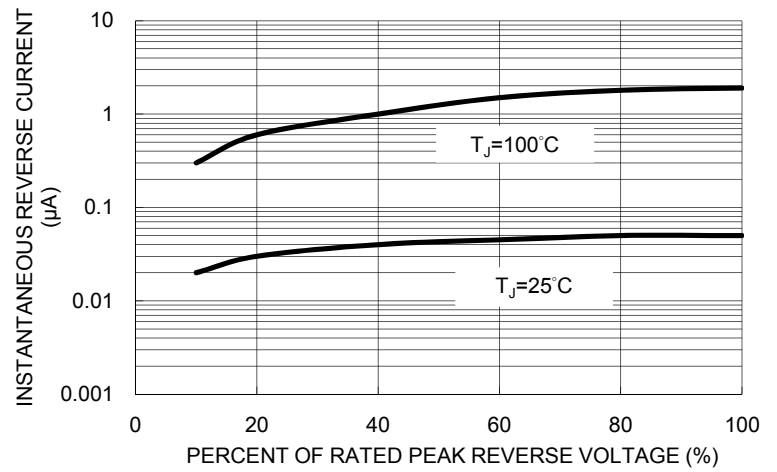


FIG. 3 MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

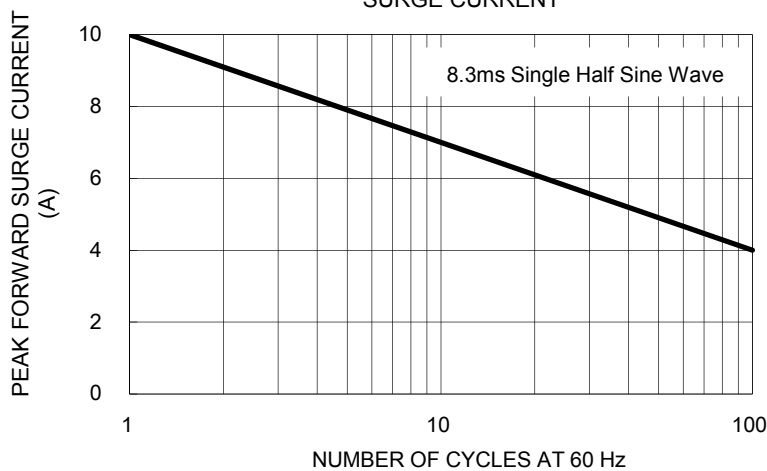


FIG. 5 TYPICAL FORWARD CHARACTERISTICS

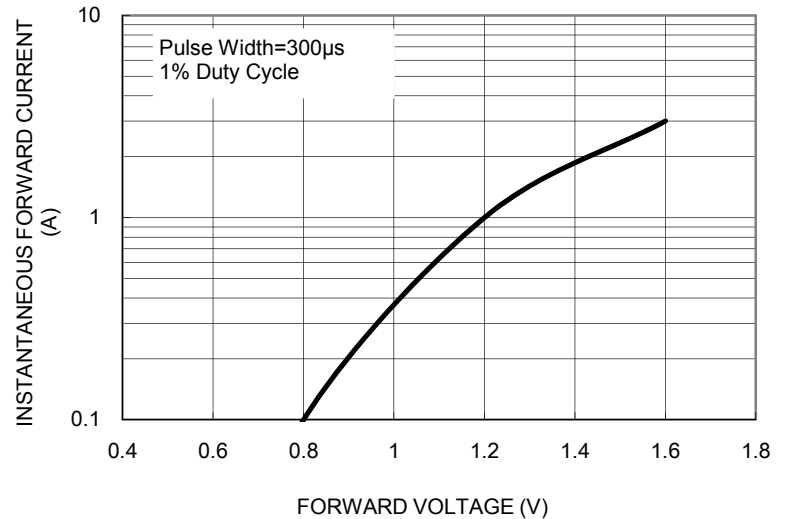


FIG. 5 TYPICAL JUNCTION CAPACITANCE

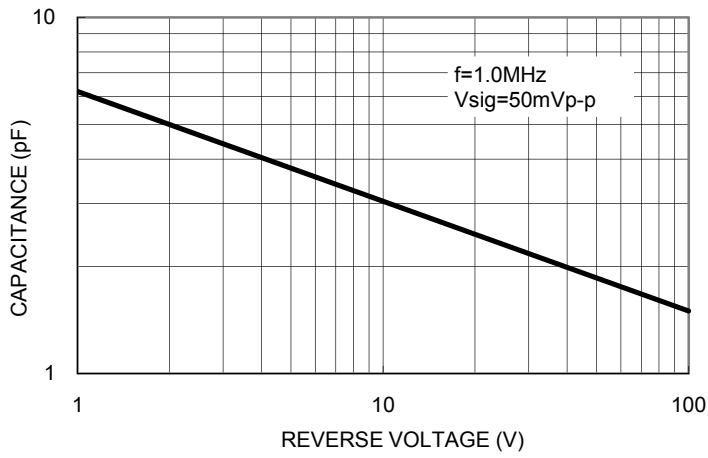
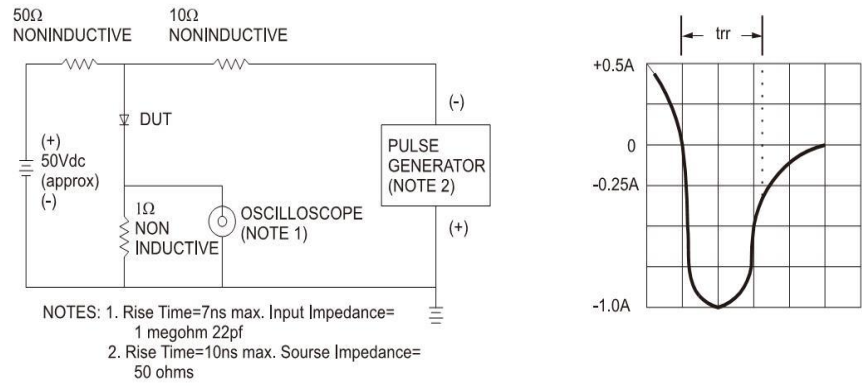
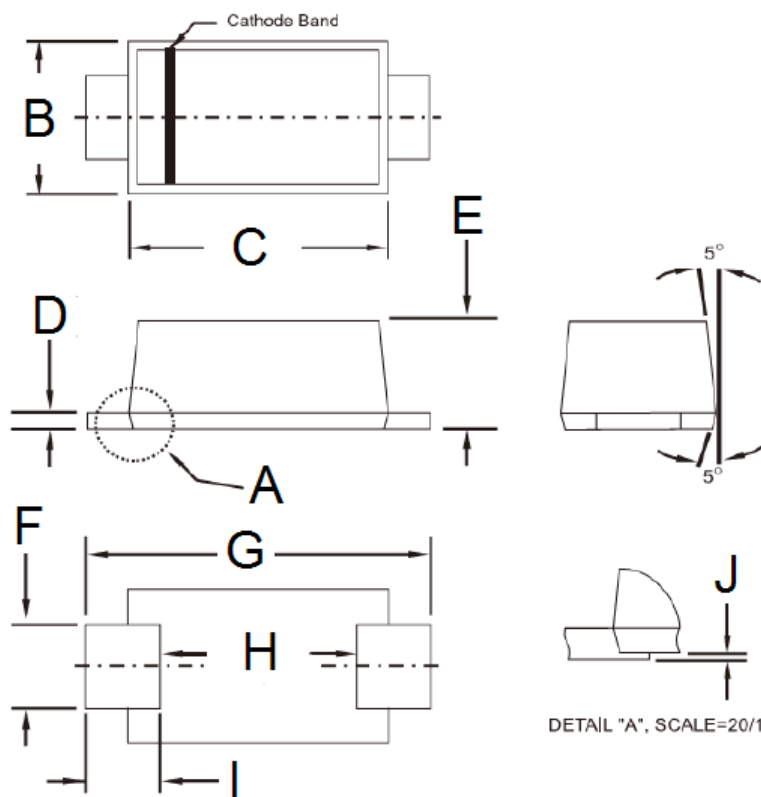


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM



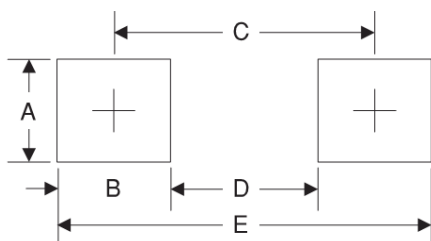
PACKAGE OUTLINE DIMENSIONS

Sub SMA



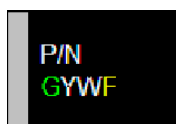
DIM.	Unit (mm)		Unit (inch)	
	Min	Max	Min	Max
B	1.70	1.90	0.067	0.075
C	2.70	2.90	0.106	0.114
D	0.16	0.30	0.006	0.012
E	1.23	1.43	0.048	0.056
F	0.80	1.20	0.031	0.047
G	3.40	3.80	0.134	0.150
H	2.45	2.60	0.096	0.102
I	0.35	0.85	0.014	0.033
J	0.00	0.10	0.000	0.004

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	1.4	0.055
B	1.2	0.047
C	3.1	0.122
D	1.9	0.075
E	4.3	0.169

MARKING DIAGRAM



- P/N = Marking Code
- G = Green compound Code
- YW = Date Code
- F = Factory Code

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